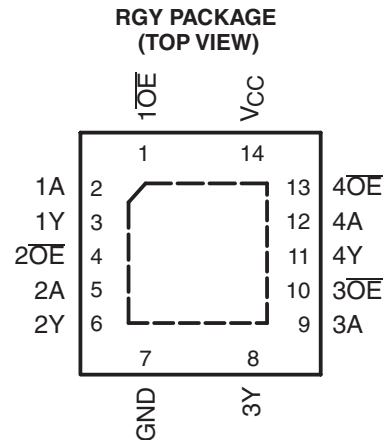


QUADRUPLE BUS BUFFER GATE WITH 3-STATE OUTPUTS

Check for Samples: [SN74LV125A-Q1](#)

FEATURES

- Qualified for Automotive Applications
- 2-V to 5.5-V V_{CC} Operation
- Typical V_{OLP} (Output Ground Bounce) <0.8 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) >2.3 V at $V_{CC} = 3.3$ V, $T_A = 25^\circ\text{C}$
- Support Mixed-Mode Voltage Operation on All Ports
- I_{off} Supports Partial-Power-Down Mode Operation



DESCRIPTION

The SN74LV125A-Q1 quadruple bus buffer gate is designed for 2-V to 5.5-V V_{CC} operation.

This device features independent line drivers with 3-state outputs. Each output is disabled when the associated output-enable (\overline{OE}) input is high.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 125°C	QFN – RGY Reel of 3000	SN74LV125AQRG1	LV125Q

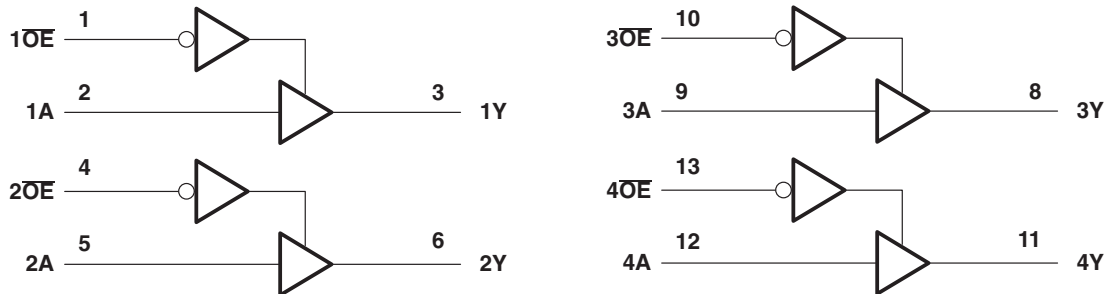
(1) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



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**FUNCTION TABLE
(EACH BUFFER)**

INPUTS		OUTPUT Y
$\overline{\text{OE}}$	A	
L	H	H
L	L	L
H	X	Z

LOGIC DIAGRAM (POSITIVE LOGIC)

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	-0.5	7	V
V_I	Input voltage range ⁽²⁾	-0.5	7	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	-0.5	7	V
V_O	Output voltage range ⁽²⁾ ⁽³⁾	-0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current		-20	mA
		$V_I < 0$		
I_{OK}	Output clamp current		-50	mA
		$V_O < 0$		
I_O	Continuous output current		± 35	mA
		$V_O = 0$ to V_{CC}		
	Continuous current through V_{CC} or GND		± 70	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾		47	$^{\circ}\text{C}/\text{W}$
		RGY package		
T_{stg}	Storage temperature range	-65	150	$^{\circ}\text{C}$

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 5.5 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51-5.

RECOMMENDED OPERATING CONDITIONS⁽¹⁾

		MIN	MAX	UNIT	
V _{CC}	Supply voltage	4.5	5.5	V	
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5	V	
		V _{CC} = 2.3 V to 2.7 V	V _{CC} × 0.7		
		V _{CC} = 3 V to 3.6 V	V _{CC} × 0.7		
		V _{CC} = 4.5 V to 5.5 V	V _{CC} × 0.7		
V _{IL}	Low-level input voltage	V _{CC} = 2 V	0.5	V	
		V _{CC} = 2.3 V to 2.7 V	V _{CC} × 0.3		
		V _{CC} = 3 V to 3.6 V	V _{CC} × 0.3		
		V _{CC} = 4.5 V to 5.5 V	V _{CC} × 0.3		
V _I	Input voltage	0	5.5	V	
V _O	Output voltage	High or low state	0	V _{CC}	V
		3-state	0	5.5	
I _{OH}	High-level output current	V _{CC} = 2 V	-50	mA	
		V _{CC} = 2.3 V to 2.7 V	-2		
		V _{CC} = 3 V to 3.6 V	-8		
		V _{CC} = 4.5 V to 5.5 V	-16		
I _{OL}	Low-level output current	V _{CC} = 2 V	50	mA	
		V _{CC} = 2.3 V to 2.7 V	2		
		V _{CC} = 3 V to 3.6 V	8		
		V _{CC} = 4.5 V to 5.5 V	16		
Δt/Δv	Input transition rise or fall rate	V _{CC} = 2.3 V to 2.7 V	200	ns/V	
		V _{CC} = 3 V to 3.6 V	100		
		V _{CC} = 4.5 V to 5.5 V	20		
T _A	Operating free-air temperature	-40	125	°C	

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
V _{OH}	I _{OH} = -50 μA	2 V to 5.5 V	V _{CC} -0.1			V
	I _{OH} = -2 mA	2.3 V	2			
	I _{OH} = -8 mA	3 V	2.48			
	I _{OH} = -16 mA	4.5 V	3.8			
V _{OL}	I _{OL} = 50 μA	2 V to 5.5 V			0.1	V
	I _{OH} = 2 mA	2.3 V			0.4	
	I _{OH} = 8 mA	3 V			0.44	
	I _{OL} = 16 mA	4.5 V			0.55	
I _I	V _I = 5.5 V or GND	0 to 5.5 V			±1	μA
I _{OZ}	V _O = V _{CC} or GND	5.5 V			±5	μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			20	μA
I _{off}	V _I or V _O = 0 to 5.5 V	0			5	μA
C _i	V _I = V _{CC} or GND	3.3 V		1.6		pF
		5 V		1.6		

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$ (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 125^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	$C_L = 50 \text{ pF}$	8.7	16.5		1	18.5	ns
t_{en}	\overline{OE}	Y		8.8	16.5		1	18.5	ns
t_{dis}	\overline{OE}	Y		7.3	18.2		1	20.5	ns
$t_{sk(o)}$							2		ns

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 125^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	$C_L = 50 \text{ pF}$	6.1	11.5		1	13	ns
t_{en}	\overline{OE}	Y		6.2	11.5		1	13	ns
t_{dis}	\overline{OE}	Y		5.5	13.2		1	15	ns
$t_{sk(o)}$							1.5		ns

SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range, $V_{CC} = 5 \text{ V} \pm 0.5 \text{ V}$ (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			$T_A = -40^\circ\text{C to } 125^\circ\text{C}$		UNIT
				MIN	TYP	MAX	MIN	MAX	
t_{pd}	A	Y	$C_L = 50 \text{ pF}$	4.3	7.5			10	ns
t_{en}	\overline{OE}	Y		4.4	7.1			10	ns
t_{dis}	\overline{OE}	Y		4	8.8			11	ns
$t_{sk(o)}$							1		ns

NOISE CHARACTERISTICS⁽¹⁾
 $V_{CC} = 3.3\text{ V}$, $C_L = 50\text{ pF}$, $T_A = 25^\circ\text{C}$

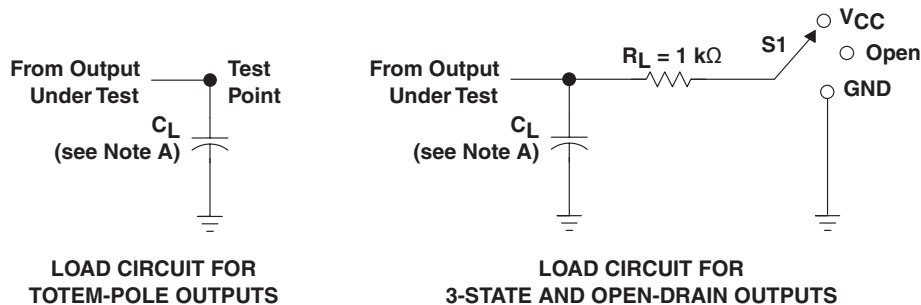
		MIN	TYP	MAX	UNIT
$V_{OL(P)}$	Quiet output, maximum dynamic V_{OL}		0.4	0.8	V
$V_{OL(V)}$	Quiet output, minimum dynamic V_{OL}		-0.3	-0.8	V
$V_{OH(V)}$	Quiet output, minimum dynamic V_{OH}		3		V
$V_{IH(D)}$	High-level dynamic input voltage	2.31			V
$V_{IL(D)}$	Low-level dynamic input voltage			0.99	V

(1) Characteristics are for surface-mount packages only.

OPERATING CHARACTERISTICS
 $T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	Outputs enabled $C_L = 50\text{ pF}$, $f = 10\text{ MHz}$	3.3 V	15.5	pF
			5 V	17.6	

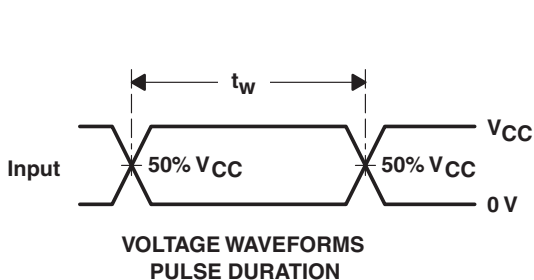
PARAMETER MEASUREMENT INFORMATION



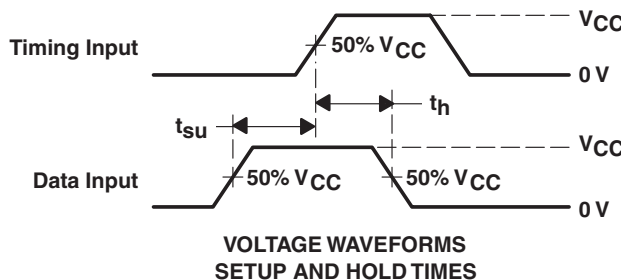
TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	V_{CC}
t_{PHZ}/t_{PZH}	GND
Open Drain	V_{CC}

LOAD CIRCUIT FOR TOTEM-POLE OUTPUTS

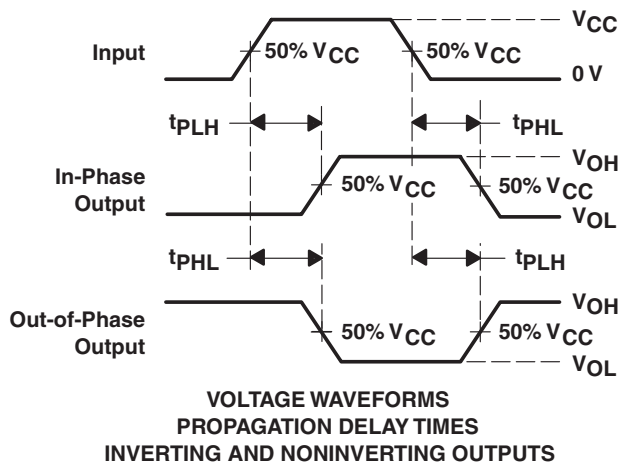
LOAD CIRCUIT FOR 3-STATE AND OPEN-DRAIN OUTPUTS



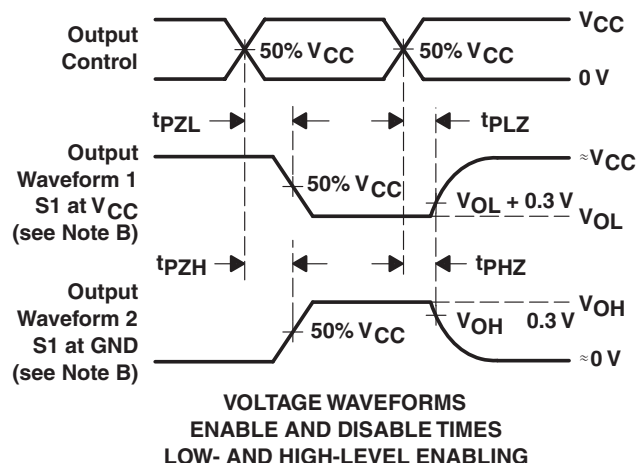
VOLTAGE WAVEFORMS PULSE DURATION



VOLTAGE WAVEFORMS SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS PROPAGATION DELAY TIMES INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS ENABLE AND DISABLE TIMES LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_r \leq 3 \text{ ns}$, $t_f \leq 3 \text{ ns}$.
 - D. The outputs are measured one at a time, with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PHL} and t_{PLH} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
SN74LV125AQRGYRQ1	ACTIVE	VQFN	RGY	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-3-260C-168 HR	Request Free Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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OTHER QUALIFIED VERSIONS OF SN74LV125A-Q1 :

- Catalog: [SN74LV125A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV125AQRGYRQ1	VQFN	RGY	14	2000	330.0	12.4	3.75	3.75	1.15	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV125AQRGYRQ1	VQFN	RGY	14	2000	367.0	367.0	35.0

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.
 - F. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - G. Package complies to JEDEC MO-241 variation BA.

RGY (S-PVQFN-N14)

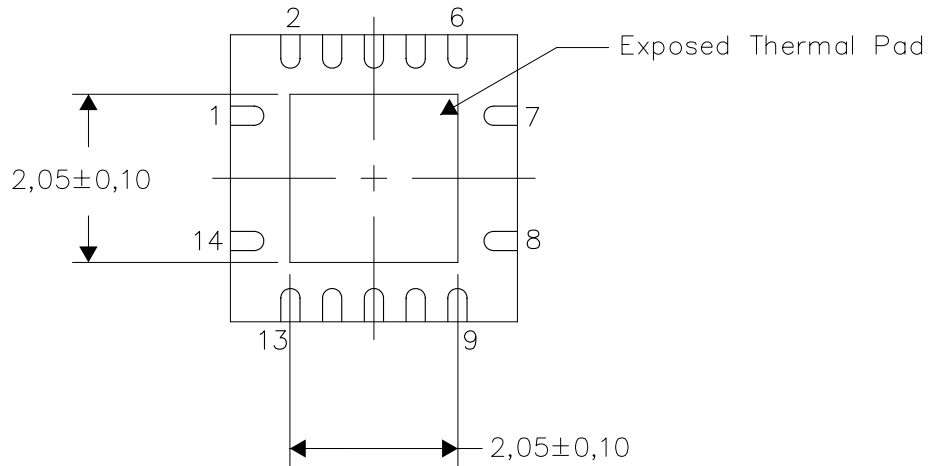
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

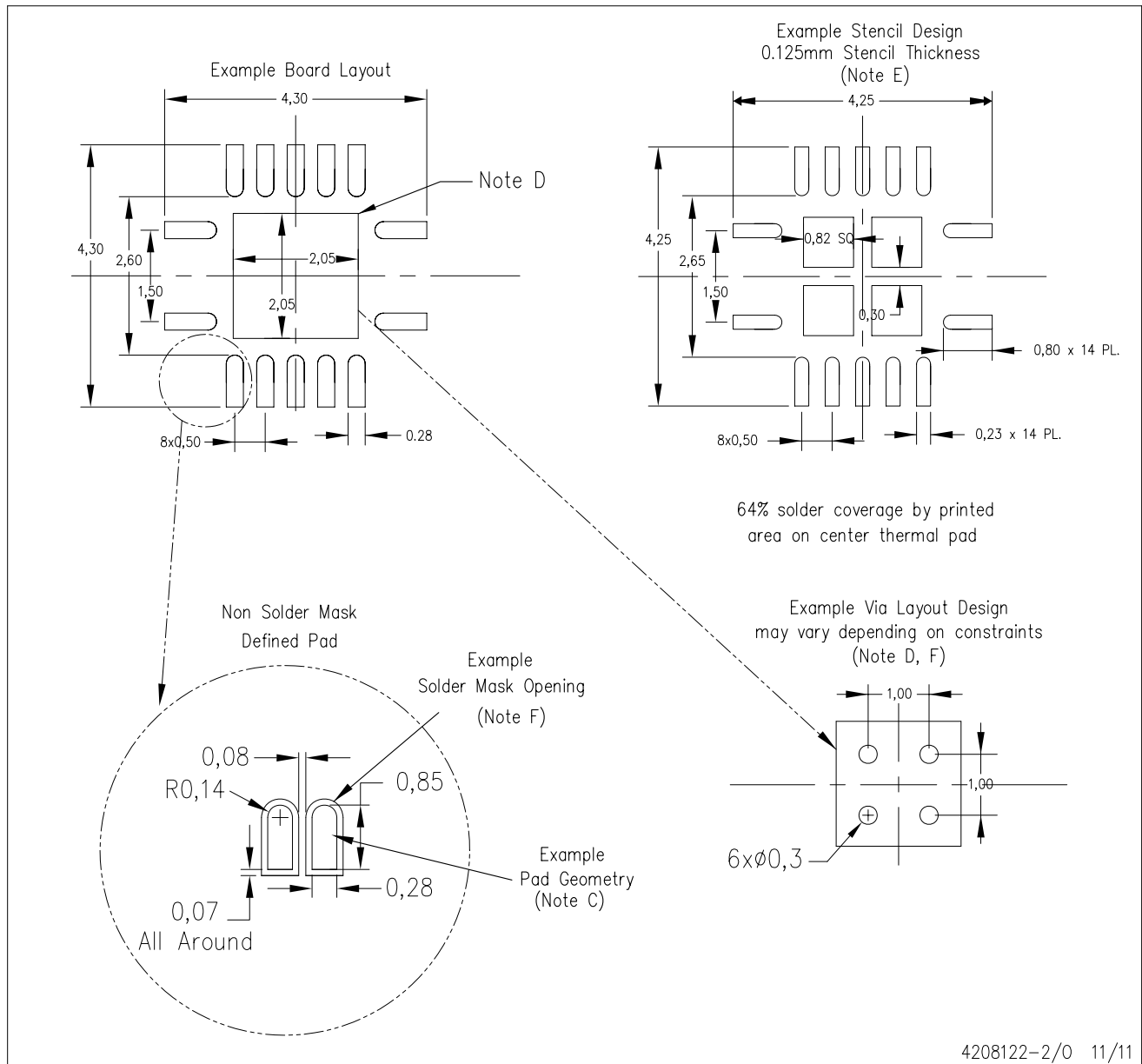
Exposed Thermal Pad Dimensions

4206353-2/0 11/11

NOTE: All linear dimensions are in millimeters

RGY (S-PVQFN-N14)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

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